

High Current, High Frequency, Power Inductors

FLAT-PAC™ FP1505 Series



Description

- Halogen Free
- 125°C maximum total operating temperature
- 7.0 x 15.0 x 5.0mm surface mount package
- · Ferrite core material
- High current handling capability, low core loss
- Designed for high speed, high current switch mode applications
- Controlled DCR tolerance for sensing circuits
- Inductance range from 100nH to 400nH

- Current range from 24 to 105 amps
- · Frequency range up to 1MHz
- RoHS compliant

Applications

- Multi-phase regulators
- Voltage Regulator Module (VRM)
- Desktop and server VRMs and EVRDs
- · Data networking and storage systems
- Notebook regulators
- Graphics cards and battery power systems
- · Point of load modules
- · DCR current sensing

Environmental Data

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (with derated current)
- Solder reflow temperature: J-STD-020D compliant

Packaging

• Supplied in tape-and-reel packaging, 744 parts per reel, 13" diameter reel

Product Specifications							
Part	OCL1	FLL ²	I _{rms} ³	I _{sat} 1⁴	I _{sat} 2⁵	DCR (m Ω)	
Number ⁷	± 10% (nH)	Min. (nH)	(Amps)	(Amps) @25°C	(Amps) @125°C	@20°C	K-factor ⁶
FP1505R1-R10-R	100	72		105	90		356.3
FP1505R1-R12-R	120	86		87	75		356.3
FP1505R1-R15-R	150	108	53	72	60	0.47 ± 7%	356.3
FP1505R1-R25-R	250	180	33	42	32	0.47 ± 7%	356.3
FP1505R1-R30-R	300	217		35	26		356.3
FP1505R1-R40-R	400	288		24	19.5		356.3

¹ Open Circuit Inductance (OCL) Test Parameters: 100kHz, 1.0V_{rms}, 0.0Adc

Data Sheet: 4365







0409 BU-SB09350 Page 1 of 4

² Full Load Inductance (FLL) Test Parameters: 100kHz, 1.0V_{rms}, I_{sat}1

3 I_{rms}: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.

⁴ I_{sat}1: Peak current for approximately 20% rolloff at +25°C.

⁵ Isat2: Peak current for approximately 20% rolloff at +125°C.

⁶ K-factor: Used to determine B_{p-p} for core loss (see graph). $B_{p-p} = K * L * \Delta I * 10^3$. B_{p-p} :(Gauss), K: (K-factor from table), L: (Inductance in nH), Δ I (Peak-to-peak ripple current in amps).

⁷ Part Number Definition: FP1505Rx-Rxx-R

[•] FP1505 = Product code and size

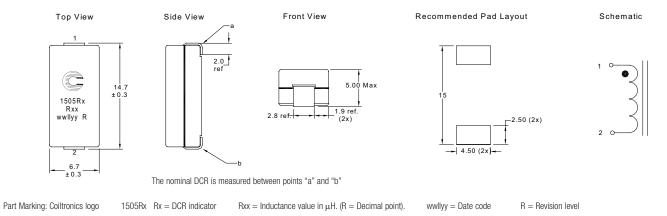
Bx= DCR indicator

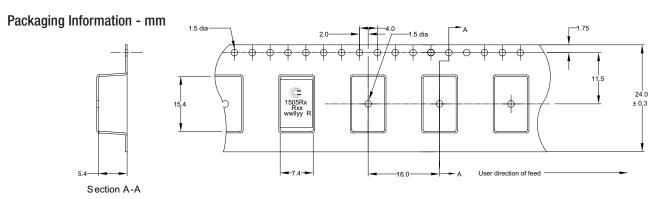
[•] Rxx= Inductance value in uH, R = decimal point

^{• -}R suffix = RoHS compliant



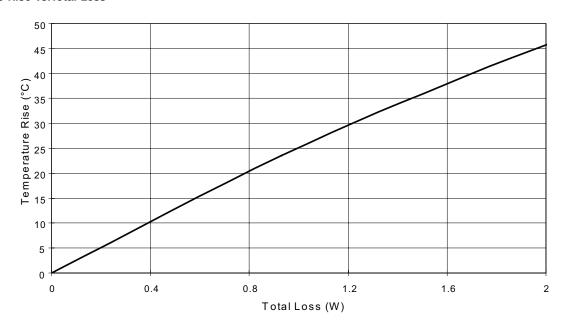
Dimensions - mm





Supplied in tape-and-reel packaging, 744 parts per reel, 13" diameter reel.

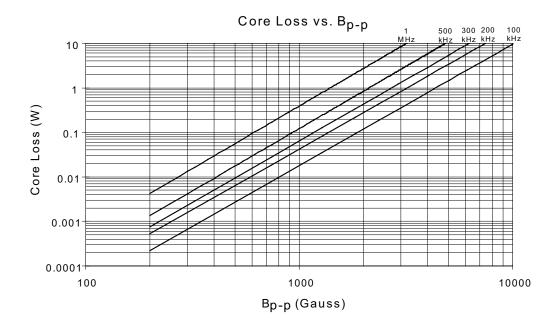
Temperature Rise vs.Total Loss



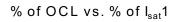
0409 BU-SB09350 Page 2 of 4 Data Sheet: 4365 **COOPER Bussmann**

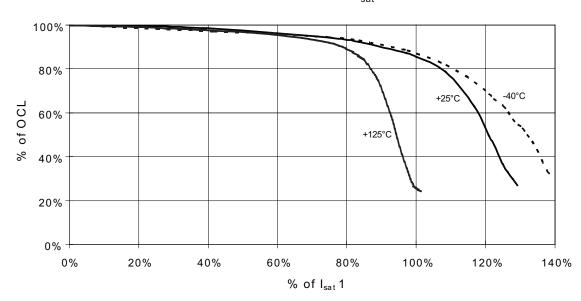


Core Loss



Inductance Characteristics





0409 BU-SB09350 Page 3 of 4 Data Sheet: 4365 **COOPER Bussmann**



Solder Reflow Profile

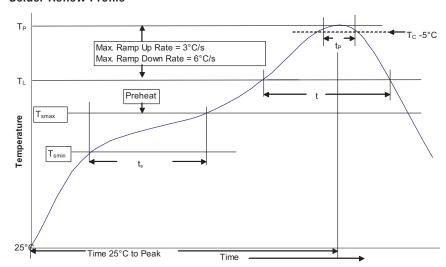


Table 1 - Standard SnPb Solder (T_C)

Package	Volume mm³	Volume mm³
Thickness	<350	≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (Tc)

Package	Volume mm ³	Volume mm³	Volume mm³
Thickness	<350	350 - 2000	>2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature		Lead (Pb) Free Solder	
• Temperature min. (T _{smin})	100°C	150°C	
Temperature max. (T _{smax})	150°C	200°C	
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds	
Average ramp up rate T _{Smax} to T _p		3°C/ Second Max.	
Liquidous temperature (TL)		217°C	
Time at liquidous (t _L)		60-150 Seconds	
Peak package body temperature (Tp)*		Table 2	
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature (T_c)		30 Seconds**	
Average ramp-down rate (T _p to T _{smax})		6°C/ Second Max.	
Time 25°C to Peak Temperature		8 Minutes Max.	
	Temperature max. (T _{Smax}) Time (T _{Smin} to T _{Smax}) (t _S) Te T _{Smax} to T _p Tre (TL) Temperature (T _p)* C of the specified classification temperature (T _c) Trate (T _p to T _{Smax})	• Temperature max. (T _{Smax}) • Time (T _{Smin} to T _{Smax}) (t _S) te T _{Smax} to T _p 3°C/ Second Max. Ire (TL) 183°C 60-150 Seconds temperature (T _P)* Table 1 °C of the specified classification temperature (T _C) 20 Seconds** rate (T _p to T _{Smax})	

 $^{^{\}star}$ Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

North America

Cooper Electronic Technologies 1225 Broken Sound Parkway NW Suite F Boca Raton, FL 33487-3533 Tel: 1-561-998-4100 Fax: 1-561-241-6640 Toll Free: 1-888-414-2645

Cooper Bussmann P.O. Box 14460 St. Louis, MO 63178-4460 Tel: 1-636-394-2877 Fax: 1-636-527-1607

Europe

Cooper Electronic Technologies Cooper (UK) Limited Burton-on-the-Wolds Leicestershire ◆ LE12 5TH UK Tel: +44 (0) 1509 882 737 Fax: +44 (0) 1509 882 786 Cooper Electronic Technologies Avda. Santa Eulalia, 290 08223 Terrassa (Barcelona). Spain

Terrassa, (Barcelona), Spain Tel: +34 937 362 812 +34 937 362 813 Fax: +34 937 362 719

Asia Pacific

Cooper Electronic Technologies 1 Jalan Kilang Timor #06-01 Pacific Tech Centre Singapore 159303 Tel: +65 278 6151 Fax: +65 270 4160

The only controlled copy of this Data Sheet is the electronic read-only version located on the Cooper Bussmann Network Drive. All other copies of this document are by definition uncontrolled. This bulletin is intended to clearly present comprehensive product data and provide technical information that will help the end user with design applications. Cooper Bussmann reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Cooper Bussmann also reserves the right to change or update, without notice, any technical information contained in this bulletin. Once a product has been selected, it should be tested by the user in all possible applications.

Life Support Policy: Cooper Bussmann does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

© 2009 Cooper Bussmann St. Louis, MO 63178 www.cooperbussmann.com







Data Sheet: 4365



^{**} Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.